



#### FABRICATION NOTES:

- 1: ALL FABRICATION ITEMS MUST MEET OR EXCEED BEST INDUSTRY PRACTICE IPC-A-600C (COMMERCIAL STANDARD).
- 2: LAMINATE MATERIAL: COPPER CLAD FR4 370 HR or EQUIVALENT.
- 3: COPPER WEIGHT: 1 OZ MIN OUTER LAYERS, 1 OZ INNER LAYERS.
- 4: FINISH BOARD THICKNESS: 0.062+/- .007 INCH.
- 5: POSITION ACCURACY: +/- .0015 INCH.
- 6: WARP AND TWIST NOT TO EXCEED .020/ INCH.
- 7: CONTROLLED IMPEDANCE LAYERS: 1 & 6
- 8: LAYER COUNT:6
- 9: VIA PADS FOR ALL UNUSED INTERNAL SIGNAL LAYERS BE REMOVED DURING BOARD MANUFACTURING.

#### PROCESS NOTES:

- 1: COPPER PLATING TO BE 0.001 MINIMUM INCH PLATED THROUGH HOLES.
- 2: CIRCUITRY ON OUTER LAYERS TO BE PLATED WITH 7 - 12 MICRO INCH GOLD OVER 50 - 80 MICRO INCH NICKEL.
- 3: SOLDERMASK BOTH SIDE: GREEN.
- 4: APPLY WHITE SILKSCREEN TO TOP AND BOTTOM SIDE OF BOARD USING SEPARATE ARTWORK.

#### TRACE WIDTHS AND ROUTING:

- 1: TRACE WIDTH CALCULATIONS ARE STARTING VALUES. BOARD SHOP MAY ADJUST TRACE WIDTHS TO COMPENSATE FOR PROCESS.
- 2: DIELECTRIC CONSTANT:FR4 370 HR.
- 3: TOP AND BOTTOM SIDE 50 OHM +/- 10% SINGLE ENDED TRACE WIDTH: 6.90 MIL.
- 4: TOP SIDE 100 OHM +/- 10% DIFFERENTIAL IMPEDENCE TRACE WIDTH: 4.10 MIL AND 5.0 MIL SPACING.

Through Holes All Drills (unless specified) +/- 0.003 (in)				
Symbol	Diameter (in)	Tolerance (in)	Plated	Quantity
A	0.008	+/- 0.003	Yes	96
B	0.010	+/- 0.003	Yes	623
C	0.025	+/- 0.003	Yes	9
D	0.028	+/- 0.003	Yes	1
E	0.032	+/- 0.003	Yes	14
F	0.036	+/- 0.003	Yes	18
G	0.040	+/- 0.003	Yes	63
H	0.042	+/- 0.003	Yes	19
J	0.042	+/- 0.003	Yes	36
K	0.043	+/- 0.003	Yes	3
L	0.067	+/- 0.003	Yes	45
M	0.078	+/- 0.003	Yes	3
◊	0.035	+/- 0.002	No	1
Ø	0.036	+/- 0.002	No	1
田	0.039	+/- 0.002	No	2
☒	0.040	+/- 0.002	No	2
□	0.097	+/- 0.001	No	1
□	0.098	+/- 0.001	No	4
×	0.125	+/- 0.002	No	4
❖	0.129	+/- 0.001	No	1